

TVS Diode Arrays

TVS Avalanche Diode Array in a Unipolar Chip Scale Package

SP0504BAC, SP0508BAC, SP0516BAC

This family of avalanche diode arrays are designed for ESD protection and offered in an ultra small chip scale package.

The multi-channel devices are used to help protect sensitive digital or analog input circuits on data, signal, or control lines with unipolar voltage levels up to 5VDC.

The state-of-the-art structure is designed to suppress ESD and other transient over-voltage events to meet the International Electrotechnical Compatibility (EMC transient immunity standards IEC 61000-4-2 for Electrostatic Discharge Requirements).

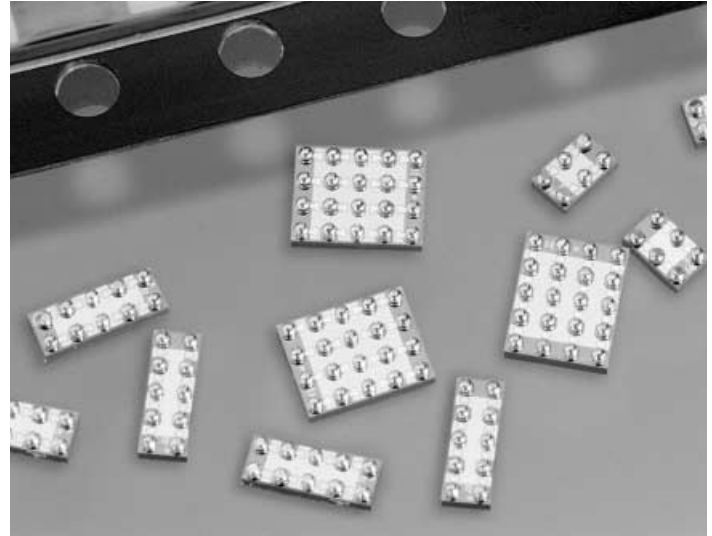
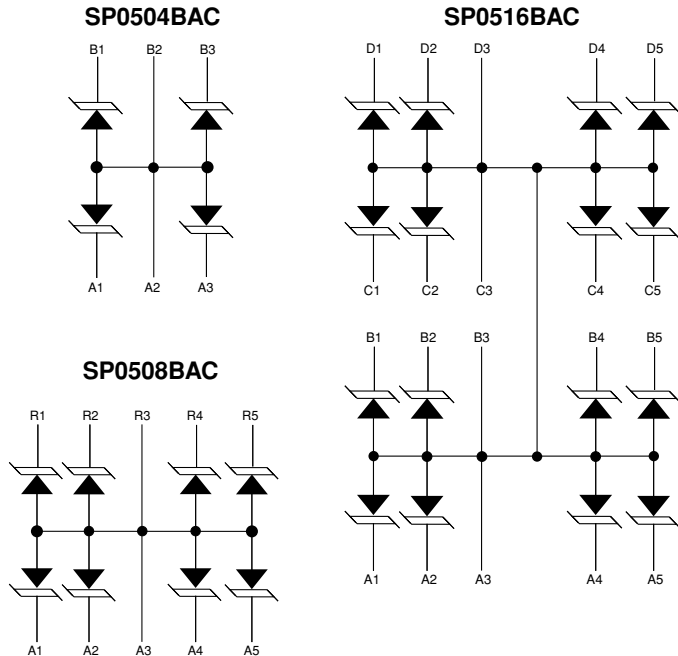
The monolithic silicon devices are comprised of specially designed structures for transient voltage suppression (TVS). The size and shape of these structures has been tailored for transient protection. The low capacitance and clamp voltage are ideal for high speed signal line protection.

Ordering Information

PART NUMBER	DIODE CHANNELS	BUMPS	CS PACKAGE SIZE (MM)	QUANTITY PER REEL
SP0504BACT	4	6	1.804 x 1.154	3500
SP0508BACT	8	10	3.104 x 1.154	3500
SP0516BACT	16	20	3.104 x 2.454	3500

NOTE: Bump pitch is 0.65mm

Schematic



Features

- An Array of 4, 8 and 16 Avalanche Diodes in a ultra small Chip Scale Package (.65mm bump pitch)
- ESD Capability per HBM Standards
 - IEC 61000-4-2, Direct Discharge.....25kV (Level 4)
 - IEC 61000-4-2, Air Discharge.....30kV (Level 4)
 - MIL STD 883C (Method 3015.7)30kV
- Signal line protection for applications up to 5VDC
- Fast response time.....< 1ns
- Low input capacitance39pF Typical
- Low clamp voltage12V Typical
- Low input leakage.....10uA Max
- Operating temperature range- 40°C to 85°C

Applications

- Cell phone handsets
- Personal Digital Assistants (PDA)
- Portable handheld equipment (Laptop, Palmtop computers)
- Computer port, keyboard (USB1.1)
- Set-Top Box (Audio and Video Ports)
- PCMCIA cards
- MP3 players
- Digital still cameras
- Digital video cameras

TVS Diode Arrays

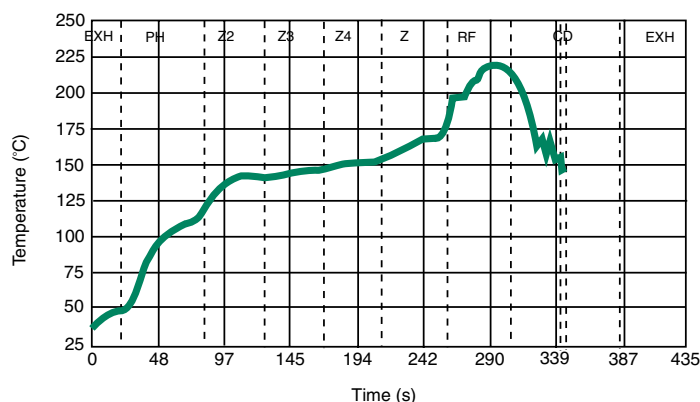
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PARAMETER	TEST CONDITIONS	MIN	TYPICAL	MAX	UNITS
Reverse Standoff Voltage	$I = 10\mu A$	± 5.5	-	-	V
Reverse Standoff Leakage Current	$V = TBD$			100	nA
Signal Clamp Voltage					
Positive	$I = 10mA$	5.6	6.8	8.0	V
Negative	$I = 10mA$	- 1.2	- 0.8	- 0.4	V
Clamp Voltage during ESD					
MIL-STD-883D Method 3015	8kV Positive		12		V
	8kV Negative		- 8		V
ESD Test Level					
IEC-61000-4-2, Contact discharge		25			kV
MIL-STD-883D Method 3015 (HBM)		30			kV
Capacitance	2.5VDC @ 1Mhz		39	47	pF
Turn on/off Time			<1		ns
Temperature Range					
Operating		- 40		85	°C
Storage		- 65		150	°C

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TVS DIODE ARRAYS

Typical Solder Reflow Thermal Profile (No-Clean Flux)



PRINTED CIRCUIT BOARD RECOMMENDATIONS

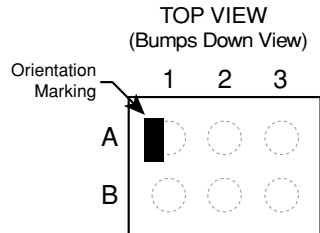
PARAMETER	VALUE
Pad Size on PCB	0.300mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.350mm Round
Solder Stencil Thickness	0.125 - 0.150mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.360mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance — Edge To Corner Ball	$\pm 50\mu m$
Solder Ball Side Coplanarity	$\pm 20\mu m$
Maximum Dwell Time Above Liquidous	60 seconds
Soldering Maximum Temperature	260°C

TVS Diode Arrays

TVS Avalanche Diode Array in a Unipolar Chip Scale Package

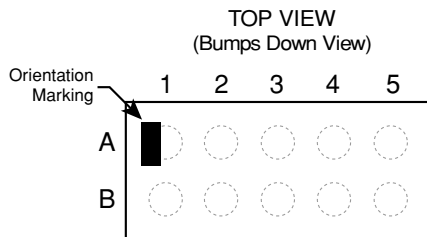
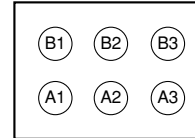
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PACKAGE / PINOUT DIAGRAMS



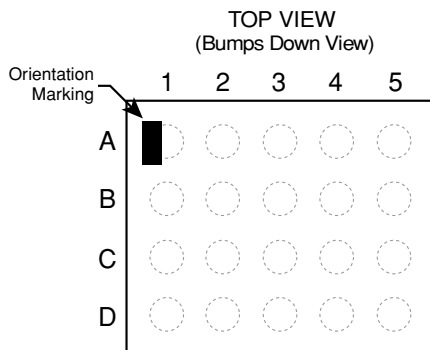
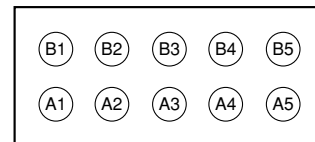
SP0504BAC
CSP Package

BOTTOM VIEW
(Bumps Up View)



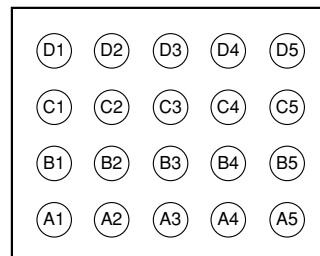
SP0508BAC
CSP Package

BOTTOM VIEW
(Bumps Up View)



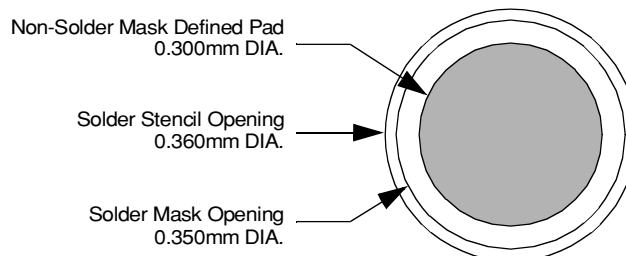
SP0516BAC
CSP Package

BOTTOM VIEW
(Bumps Up View)



Notes:

1) These drawings are not to scale.



TVS Diode Arrays

TVS Avalanche Diode Array in a Unipolar Chip Scale Package

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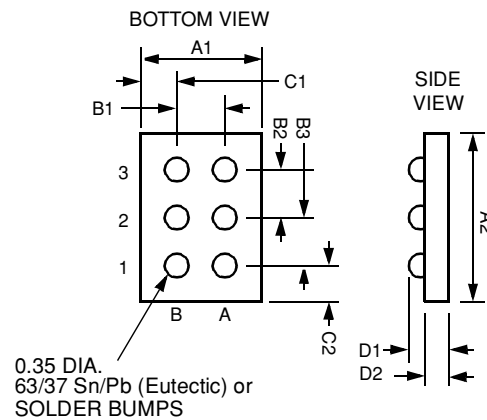
SP0504BAC 6-bump

CSP Mechanical Specifications

The SP0504BAC devices are packaged in a 6-bump custom Chip Scale Package (CSP). Dimensions are presented below.

PACKAGE DIMENSIONS						
Package		Custom CSP				
Bumps		6				
Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A1	1.109	1.154	1.199	0.0437	0.0454	0.0472
A2	1.759	1.804	1.849	0.0693	0.0710	0.0728
B1	0.645	0.650	0.655	0.0254	0.0256	0.0258
B2	0.645	0.650	0.655	0.0254	0.0256	0.0258
B3	0.645	0.650	0.655	0.0254	0.0256	0.0258
C1	0.202	0.252	0.302	0.0080	0.0099	0.0119
C2	0.202	0.252	0.302	0.0080	0.0099	0.0119
D1	0.600	0.644	0.687	0.0236	0.0253	0.0271
D2	0.356	0.381	0.406	0.0140	0.0150	0.0160
# per tape and reel		3500 pieces				
Controlling dimension: millimeters						

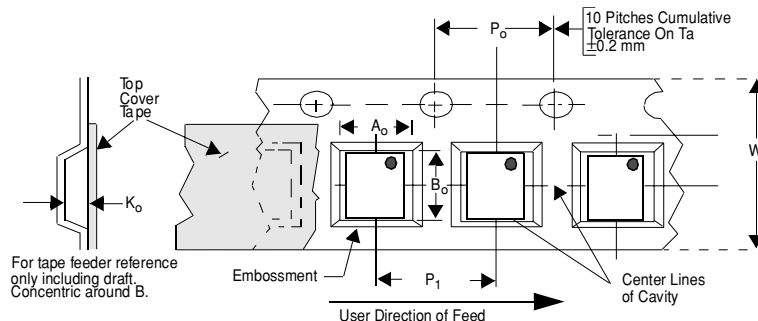
Mechanical Package Diagrams



DIMENSIONS IN MILLIMETERS

CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B ₀ X A ₀ X K ₀	TAPE WIDTH W	REEL DIA.	QTY PER REEL	P ₀	P ₁
SP0504BAC	1.804 X 1.154 X 0.644	1.98 X 1.32 X 0.91	8mm	178mm (7")	3500	4mm	4mm



Tape Specifications

TVS Diode Arrays

TVS Avalanche Diode Array in a Unipolar Chip Scale Package

SP0504BAC, SP0508BAC, SP0516BAC

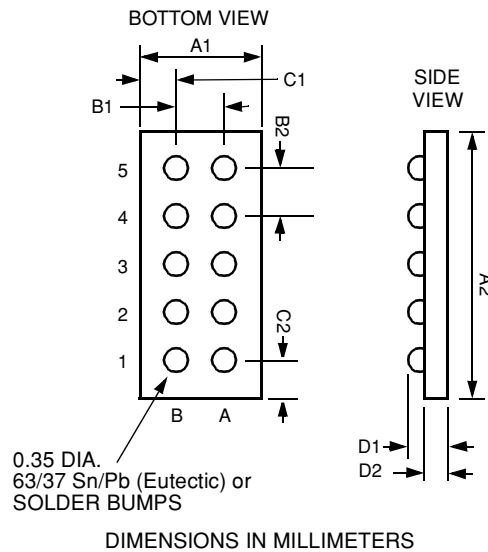
SP0508BAC 10-bump

CSP Mechanical Specifications

The SP0508BAC devices are packaged in a 6-bump custom Chip Scale Package (CSP). Dimensions are presented below.

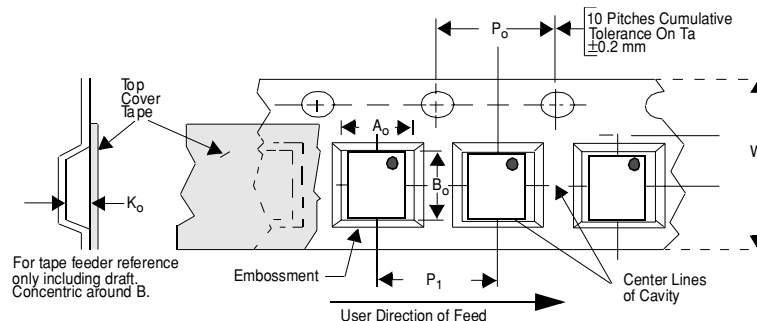
PACKAGE DIMENSIONS						
Package	Custom CSP					
Bumps	10					
Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A1	1.109	1.154	1.199	0.0437	0.0454	0.0472
A2	3.059	3.104	3.149	0.1204	0.1222	0.1240
B1	0.645	0.650	0.655	0.0254	0.0256	0.0258
B2	0.645	0.650	0.655	0.0254	0.0256	0.0258
C1	0.202	0.252	0.302	0.0080	0.0099	0.0119
C2	0.202	0.252	0.302	0.0080	0.0099	0.0119
D1	0.600	0.644	0.687	0.0236	0.0253	0.0271
D2	0.356	0.381	0.406	0.0140	0.0150	0.0160
# per tape and reel	3500 pieces					
Controlling dimension: millimeters						

Mechanical Package Diagrams



CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B ₀ X A ₀ X K ₀	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P ₀	P ₁
SP0508BAC	3.104 X 1.154 X 0.644	3.28 X 1.32 X 0.81	8mm	178mm (7")	3500	4mm	4mm



Tape Specifications

TVS Diode Arrays

TVS Avalanche Diode Array in a Unipolar Chip Scale Package

SP0504BAC, SP0508BAC, SP0516BAC

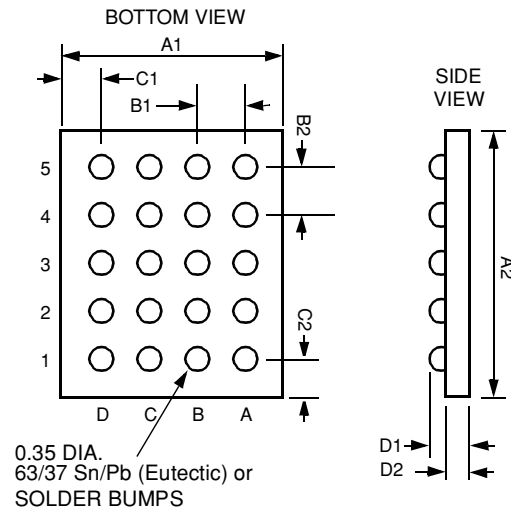
SP0516BAC 20-bump

CSP Mechanical Specifications

The SP0516BAC devices are packaged in a 20-bump custom Chip Scale Package (CSP). Dimensions are presented below.

PACKAGE DIMENSIONS						
Package		Custom CSP				
Bumps		20				
Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A1	2.409	2.454	2.499	0.0948	0.0966	0.0984
A2	3.059	3.104	3.149	0.1204	0.1222	0.1240
B1	0.645	0.650	0.655	0.0254	0.0256	0.0258
B2	0.645	0.650	0.655	0.0254	0.0256	0.0258
C1	0.202	0.252	0.302	0.0080	0.0099	0.0119
C2	0.202	0.252	0.302	0.0080	0.0099	0.0119
D1	0.600	0.644	0.687	0.0236	0.0253	0.0271
D2	0.356	0.381	0.406	0.0140	0.0150	0.0160
# per tape and reel		3500 pieces				
Controlling dimension: millimeters						

Mechanical Package Diagrams

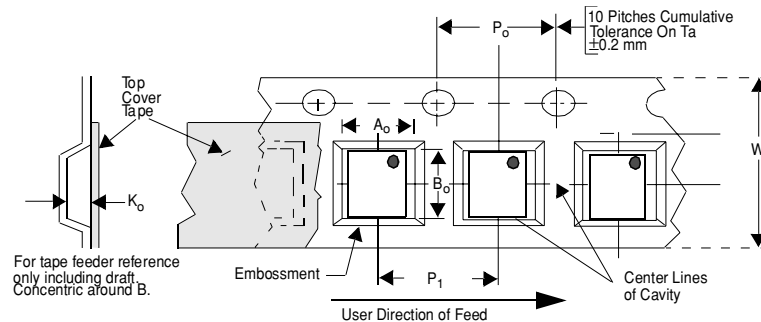


DIMENSIONS IN MILLIMETERS

SILICON PROTECTION
CIRCUITS

CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) $B_0 \times A_0 \times K_0$	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P_0	P_1
SP0516BAC	3.104 X 2.454 X 0.644	3.28 X 2.64 X 0.86	8mm	178mm (7")	3500	4mm	4mm



Tape Specifications